

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	("6390690") or ("6600853") or ("4465333") or ("6257771") or ("6623177") or ("20030128933") or ("20030219217").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:12
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S8	19	("3351816").URPN.	USPAT	OR	OFF	2004/11/30 12:11
S9	9	("RE27089").URPN.	USPAT	OR	OFF	2004/11/30 12:14
S10	70	("5282312").URPN.	USPAT	OR	OFF	2004/11/30 13:47
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S13	27	("5421083").URPN.	USPAT	OR	OFF	2004/11/30 15:21
S14	0	("6787710").URPN.	USPAT	OR	OFF	2004/11/30 15:30
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S19	21	S18 and (fiber\$1 or wave\$guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 15:44

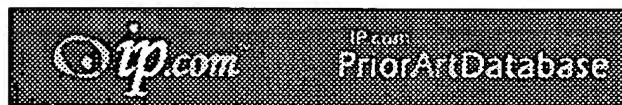
S20	127493	(optical or opto) with (via\$1 or hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
S21	1795	S20 and (copper with (clad\$1 or cladding\$1 or laminate\$1 or layer\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
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S23	187	S22 not S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:03
S24	171	S23 not (S4 or S5 or S7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:09
S25	43	S24 and ((optical with fiber\$1) or wave\$guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:09
S26	864	S20 and 385/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
S27	49	S21 and 385/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16

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S30	13	S28 and prepreg	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:39
S31	2	S28 and prepreg and ((optical with fiber\$1) or wave\$guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:39
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Result # 1      Relevance:

[PREVIEW](#)**Via Punching Device for Multi-Layered Ceramic Substrates**

29-Jan-2005      IPCOM000037316D      English

A technique is described whereby the mechanical punching of via holes in multi-layered ceramic substrates is controlled through the use of independently controlled punching stations. The new via punching device improves upon the improvement of a previous system which uses only a ...

Result # 2      Relevance:

[PREVIEW](#)**Minimal Metal Mask for Reactive Ion Etching Polyimide**

13-Feb-2005      IPCOM000055528D      English

The fabrication of thin film modules of multi-layered ceramic substrates for packaging chips requires the making of via holes through a thermal resin which serves as a dielectric between transmission line levels and transmission line-ground plane levels.

Result # 3      Relevance:

[PREVIEW](#)**SIP: Session Initiation Protocol (RFC3261)**

09-Aug-2002      IPCOM00009156D      English

This document describes Session Initiation Protocol (SIP), an application control (signaling) protocol for creating, modifying, and terminating sessions involving one or more participants. These sessions include Internet telephony, multimedia distribution, and ...

Result # 4      Relevance:

[PREVIEW](#)**RETENTION OF PHOSPHORUS IN SILICON BENEATH SILICIDE CONTACTS DURING HIGH TEMPERATURE**

19-Oct-2001      IPCOM000005621D      English

After metal contacts and short-range interconnects are deposited there is often the need to carry out processing at high temperature. Compound formation, grain size enhancement, contact improvement, glass reflow for tapering of via holes in thick doped ...

Result # 5      Relevance:

[PREVIEW](#)**Manufacturing process to fabricate co-planar multi-level printed circuit boards**

20-Jun-2003      IPCOM000014863D      English

A manufacturing process for insuring co-planarity of epoxy printed circuit boards fabricated with more than one level on a side having different surface dimensions is described. Individual layers of printed circuit material (comprised of differing circuit layout ...

Result # 6      Relevance:

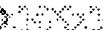
[PREVIEW](#)**Method for Forming Wiring Patterns and Vias on a Substrate**

29-Jan-2005      IPCOM000036834D      English

This article describes a new method of defining wiring patterns

pure metals or metallic alloys on various ceramic greensheets, i fired ceramic substrates, or polymer surfaces. The disclosed prc capability for obtaining higher resolution ...

---

Result # 7 Relevance: 

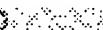


**Method for Structural Characterization of Bi-Layer for Use in Personal Care Products via Microscopy a Analysis**

14-Dec-2004 IPCOM000033526D English

A methodology has been developed to characterize the structur multi-layer absorbent materials. The method is able to detect a z-distribution of polypropylene and cellulose components. Outpi method was used to determine that the ...

---

Result # 8 Relevance: 

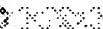


**Single-Crystal Silicon Embedded With Insulated Co Wires**

28-Jan-2005 IPCOM000036028D English

In packaging technology, a generic problem is that the packag tend to have a different thermal expansion coefficient from that Consequently, upon thermal cycling during operation a shear st on those solder balls that join the chip and ...

---

Result # 9 Relevance: 



**Network File System (NFS) version 4 Protocol (RFC**

30-Apr-2003 IPCOM000012311D English

The Network File System (NFS) version 4 is a distributed filesys which owes heritage to NFS protocol version 2, RFC 1094, and 1813. Unlike earlier versions, the NFS version 4 protocol suppo file access while integrating support ...

---

Result # 10 Relevance: 



**Towards Requirements for IP Routers (RFC1716)**

12-Sep-2000 IPCOM00003963D English

The goal of this work is to replace RFC-1009, Requirements for Gateways ([INTRO:1]) with a new document.

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**Search query:** via AND holes AND layered

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Result # 11      Relevance: 

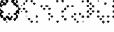
 [PREVIEW](#)

**Silver halide photographic light-sensitive material super-rapid processing**

12-Sep-2000      IPCOM000000670D      English

A silver halide photographic light-sensitive material comprising having the first photographic structural layer comprising one or a side of the support and the second photographic structural layer one or more layers on the other side of ...

---

Result # 12      Relevance: 

 [PREVIEW](#)

**Exhalation duct**

12-Sep-2000      IPCOM000000800D      English

An exhalation duct is formed from a gas impermeable covering material extending through the length of the duct to define cylindrical opening. A lower end of the duct is formed with a plurality of exhalation holes or openings in the covering ...

---

Result # 13      Relevance: 

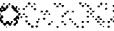
 [PREVIEW](#)

**Efficient Two Layered Organic Photovoltaic Device**

03-Mar-2005      IPCOM000085960D      English

For organic light-absorbing species at a solid-solid interface, efficient photoactivated free-carrier generation has so far been limited by (silver halide photography) or by the requirement of very high bias (electrophotography). Yet the solar ...

---

Result # 14      Relevance: 

 [PREVIEW](#)

**NFS version 4 Protocol (RFC3010)**

17-Aug-2001      IPCOM000005202D      English

NFS (Network File System) version 4 is a distributed file system which owes its heritage to NFS protocol versions 2 [RFC1094] and 3 [RFC1813]. In earlier versions, the NFS version 4 protocol supports traditional while integrating support for file ...

---

Result # 15      Relevance: 

 [PREVIEW](#)

**Requirements for Internet gateways - draft (RFC0111)**

13-Jul-2001      IPCOM000004983D      English

The following sections are intended as an introduction and background for those unfamiliar with the DARPA Internet architecture and the Internet gateway model. General background and discussion on the Internet architecture and supporting protocol suite can be found in ...

---

Result # 16      Relevance: 

 [PREVIEW](#)

**Cylindrical keyed coupling for composite propulsions**

12-Sep-2000      IPCOM00001626D      English

A coupling for a torsional drive includes a rotatable shaft, an outer housing which has a keyway comprising a half-round groove. A rotatable sleeve is rotatably mounted around the shaft and coaxial with the shaft has an inner surface ...

a second keyway, the second keyway also ...

---

Result # 17      Relevance:  

**Softshell protective mask**

12-Sep-2000      IPCOM000001350D      English

Form-fitting, comfortable, soft-shell protective apparel, commonly known as a softshell jacket or softshell vest, comprising a mask, for protecting the head, upper body and respiratory tract from chemical/biological agents and toxins and radioactive particles. The jacket is easy-to-put-on, heat and moisture-dissipating ...

---

Result # 18      Relevance:  

**Advice for Internet Subnetwork Designers AUTHOF (RFC3819)**

09-Jul-2004      IPCOM000029724D      English

This document provides advice to the designers of digital communication equipment, link-layer protocols, and packet-switched local networks (collectively referred to as subnetworks), who wish to support these protocols but may be unfamiliar with the Internet ...

---

Result # 19      Relevance:  

**Method for high-density semiconductor packages fabricated on continuous reels**

16-Jun-2004      IPCOM000029161D      English

Disclosed is a method for high-density semiconductor packages substrates fabricated on continuous reels. Benefits include improved functionality, improved performance, improved reliability, and reduced cost.

---

Result # 20      Relevance:  

**Requirements for IP Version 4 Routers (RFC1812)**

13-Sep-2000      IPCOM000004069D      English

This memo replaces for RFC 1716, "Requirements for Internet Gateways" ([INTRO:1]).

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Result # 21 Relevance:

[PREVIEW](#)**Transparent Content Negotiation in HTTP (RFC2291)**

13-Sep-2000 IPCOM000002858D English

HTTP allows web site authors to put multiple versions of the same document under a single URL. Transparent content negotiation is an extensible negotiation mechanism, layered on top of HTTP, for automatically selecting the best version when the URL is accessed. This ...

Result # 22 Relevance:

[PREVIEW](#)**Split barrel insulation displacing connector**

11-Sep-2000 IPCOM000000001D English

A split-barrel connector terminal is presented wherein a wire connector is released as a new wire is being connected. This feature is achieved by aperture (13) located a predetermined distance from the end of slot (12). When insertion tool (51) ...

Result # 23 Relevance:

[PREVIEW](#)**Some Internet Architectural Guidelines and Philosophies (RFC3439)**

11-Dec-2002 IPCOM000010524D English

This document extends RFC 1958 by outlining some of the architectural guidelines to which architects and designers of Internet backbone routers should adhere. We describe the Simplicity Principle, which states that complexity is the primary mechanism that impedes ...

Result # 24 Relevance:

[PREVIEW](#)**Requirements for Internet gateways (RFC1009)**

12-Sep-2000 IPCOM000001812D English

The following material is intended as an introduction and background for those unfamiliar with the Internet architecture and the Internet gateway. General background and discussion on the Internet architecture and supporting protocol suite can be found in the DDN ...

Result # 25 Relevance:

[PREVIEW](#)**Performance Enhancing Proxies Intended to Mitigate Related Degradations (RFC3135)**

21-Aug-2001 IPCOM000005319D English

This document is a survey of Performance Enhancing Proxies (PEPs) employed to improve degraded TCP performance caused by characteristics of specific link environments, for example, in satellite, wireless WiFi, or wireless LAN environments. Different types of ...

Result # 26 Relevance:

[PREVIEW](#)**SDP: Session Description Protocol (RFC2327)**

13-Sep-2000 IPCOM000002894D English

This document defines the Session Description Protocol, SDP. SDP is used for describing multimedia sessions for the purposes of session ...

session invitation, and other forms of multimedia session initiat

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Result # 27 Relevance: 



**Report of IAB Workshop on Security in the Internet Architecture - February 8-10, 1994 (RFC1636)**

12-Sep-2000 IPCOM000002472D English

This document is a report on an Internet architecture workshop organized by the IAB and held at USC Information Sciences Institute on February 8-10, 1994. This workshop generally focused on security issues in the Internet architecture.

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Result # 28 Relevance: 



**Use of IPsec Transport Mode for Dynamic Routing**

25-Sep-2004 IPCOM0000031435D English

IPsec can secure the links of a multihop network to protect communication between trusted components, e.g., for a secure virtual network or virtual private network (VPN). Virtual links established by IPsec can conflict with routing and forwarding ...

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Result # 29 Relevance: 



**Loader Debugger Protocol (RFC0909)**

13-Sep-2000 IPCOM000003959D English

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Result # 30 Relevance: 



**Heterojunction D.sup.- (or A.sup.+) millimeter and submillimeter wave detector**

12-Sep-2000 IPCOM000000095D English

A solid state detector for use in detecting submillimeter and millimeter radiation. The solid state detector comprises a semiconductor structure having alternating thin epitaxial layers of GaAs and AlGaAs doped with elements having the same conductivity type. Because ...

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